

JEM America Introduces New Probe Card for Advanced Packaging

Crown Shaped Probe Tips Offer Highly Reliable Contact, No Damage to the Bump, Minimal Probe Tip Wear and Minimal Probe Marks

FREMONT, Calif.--(BUSINESS WIRE) --Nov. 9, 2005-- JEM America, a subsidiary of Japan Electronic Materials Corporation (JEM), has introduced a new series of probe cards aimed at the advanced packaging techniques for flip chips, BGAs, CSPs, and a wide variety of area arrays (solder bumps or Cu bumps).

The VS (Vertical Spring) Series probe cards feature crown shaped probe tips rather than the more common flat or pointed tips. This allows for more reliable contact, minimal tip wear and minimal probe marks. As the probe card tests the circuit, the test results are more reliable with the VS-Series probe cards. That is important because it can minimize the need for re-test, which is very time consuming and expensive. Since the crown tip provides four contact points between tip and bump, the contact resistance is more stable. The new crown tips can be precisely positioned on the DUT (Device Under Test) with accuracy and planarity. They can measure any solder ball material, including eutectic, lead-free, and high-melting point solder.

Also, the bump is not damaged as it can be using the flat tip or round tip probes, because the crown tip glides lightly onto the bump. This is important in the more advanced packaging techniques for flip chip devices because the bumps are becoming smaller and closer together. The less damage to the bumps, the easier the bumps can reflow when the circuit is connected to the package. In addition, voids in packaging can be minimized due to less height deviation between probed bumps and non-probed bumps.

Another benefit of the VS-Series probe cards is that individual probes and probe head unit can easily be removed from the card and replaced, which makes repair easy and more cost effective.

About JEM America: JEM America Corp. is a subsidiary of JEM (Japan Electronic Materials Corporation), a world leader in probe card manufacturing. Established in May of 1987, JEM America is a supplier of technically advanced, high-quality probe cards and tester interfaces. JEM manufactures a diversified line of probing products: cantilever, vertical and special-applications probe cards. JEM probe cards are used in technologies such as Linear, Memory, Gate Array, Microprocessor, Power IC, ASIC, LCD driver, Thermal Head, Diode, Optical IC, ECL, and GaAs. For more information, contact www.jemam.com.